

FOR IMMEDIATE RELEASE

## **Celsia Launches NanoSpreader™ Cooling Solution for AMD Based 1U Servers**

*Industry first vapor chamber solution for 1U AMD Opteron servers tested to be sixty-two percent lighter and sixteen percent better performing than solid copper heat sinks*

SAN JOSE, California, January 8, 2009 – Celsia Technologies (OTCBB: CSAT) has launched a high efficiency vapor chamber based heat sink used to cool AMD's latest generation of quad core Opteron processors. The Celsia 1U Socket F heat sink is available to computer OEMs and ODMs and will provide both weight savings and performance enhancements over traditional solid copper solutions.

“Space constrained, high power applications are precisely the areas where NanoSpreader™ based solutions beat the competition,” commented Joseph Formichelli, Celsia’s CEO. “We started working with AMD last year to develop a higher performing alternative to the ubiquitous solid copper with copper fin design. The result of this collaboration is what we believe to be an industry first vapor chamber thermal solution for 1U servers.”

Currently listed as a reference design on the AMD developers’ web site, the Celsia model 401-AM-001 has been tested to perform sixteen percent better than solid copper/copper fin alternatives. Additionally, a sixty-two percent weight savings means less stress on the retention mechanism and processor. Available at prices starting at \$14.99, this new heat sink can be used with any Socket F 1U server and is available to OEMs and ODMs immediately. To learn more about this product visit [http://celsiatech.com/product\\_datasheets.asp](http://celsiatech.com/product_datasheets.asp).

### **About Celsia Technologies**

Celsia Technologies is a full solution provider and licensor of thermal management products and technology for the PC (server, notebook, desktop), consumer electronics, and LED lighting / display industries. The company, working with many of the largest processor manufacturers, OEMs, and display manufacturers, is a leader in developing and commercializing next-generation cooling solutions built on patented micro thermofluidic technology. Celsia Technologies’ extensive intellectual property portfolio includes patents registered in Korea, the U.S., Japan and Taiwan, with patents pending in the EU, Russia, India and China. For more information, visit [celsiatech.com](http://celsiatech.com).

### **Forward Looking Statements**

*This press release contains forward-looking statements, involving risks and uncertainties. Such statements are based on management’s current expectations and are subject to certain factors, risks, and uncertainties that may cause actual results, events and performance to differ materially from those referred to or implied by such statements. In addition, actual future results may differ materially from those anticipated, depending on a variety of factors which include, but are not limited to, Celsia Technologies’ ability to attract investors, Celsia Technologies’ future operating results, and general economic conditions affecting consumer spending, including uncertainties relating to global political conditions, such as terrorism and the conflict with Iraq. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as*

*of the date hereof. Celsia Technologies does not intend to update any of the forward-looking statements after the date of this release to conform these statements to actual results or to changes in its expectations, except as may be required by law.*

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